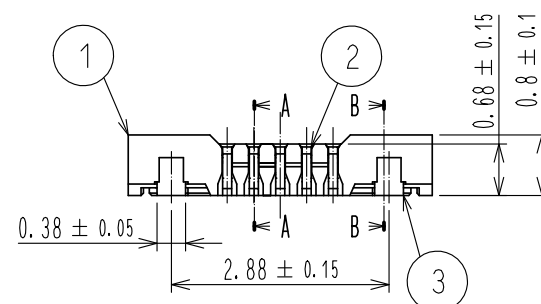


NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX

2. CONTACT PLATING SPECIFICATIONS.

CONTACT AREA : GOLD 0.05  $\mu$ m MIN

SMT LEAD : GOLD 0.05  $\mu$ m MIN

UNDERPLATING : NICKEL 1  $\mu$ m MIN

( SURFACE : SEALING )

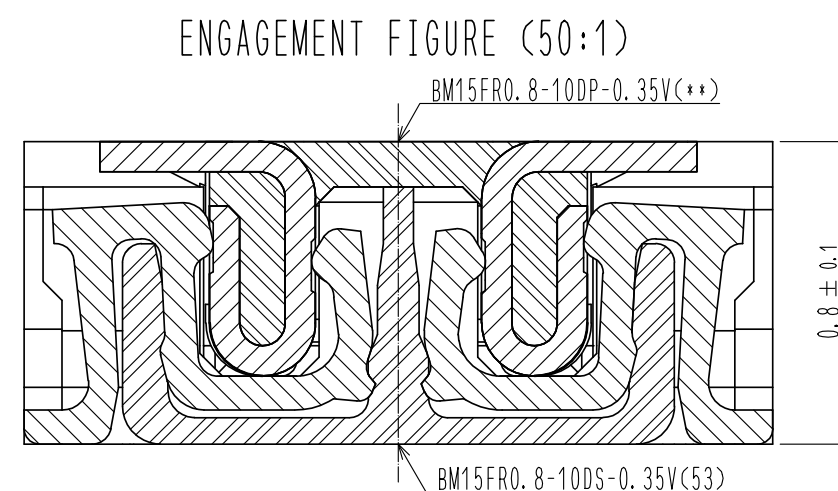
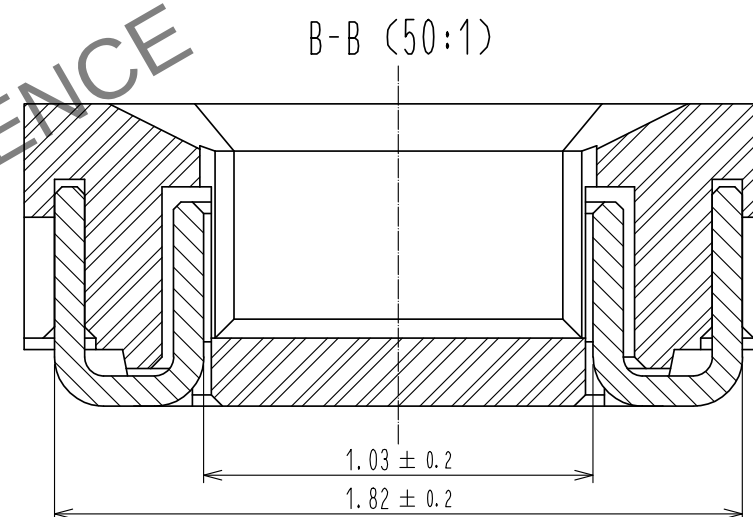
3. REINFORCED METAL FITTINGS LOCK

SMT LEAD : GOLD 0.05  $\mu$ m MIN

UNDERPLATING : NICKEL 1  $\mu$ m MIN

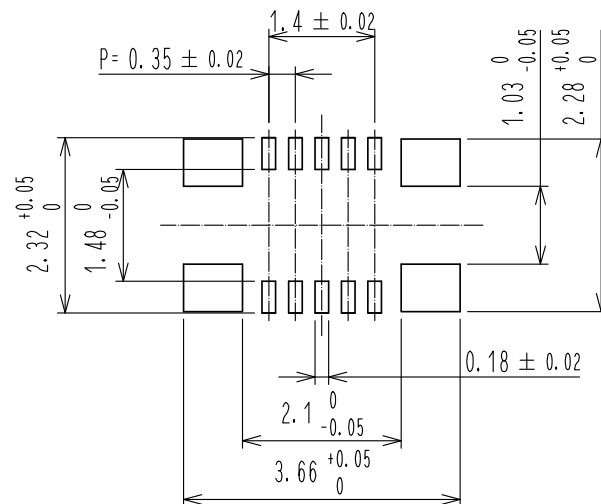
( SURFACE : SEALING )

4. CAV NO. AND HRS MARK MAY BE INDICATED IN APPROX POSITION SHOWN.

[illegible]

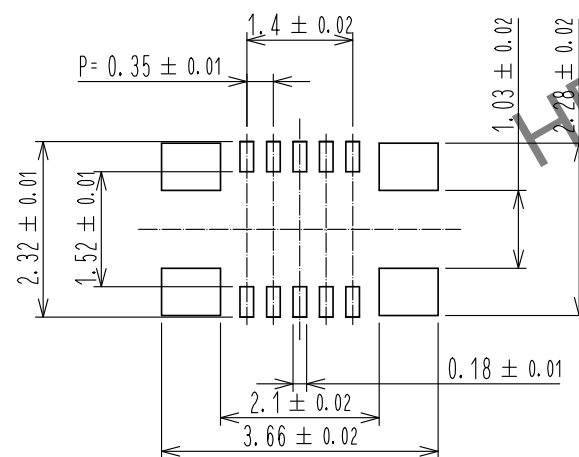
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### ◆ RECOMMENDED PCB LAYOUT

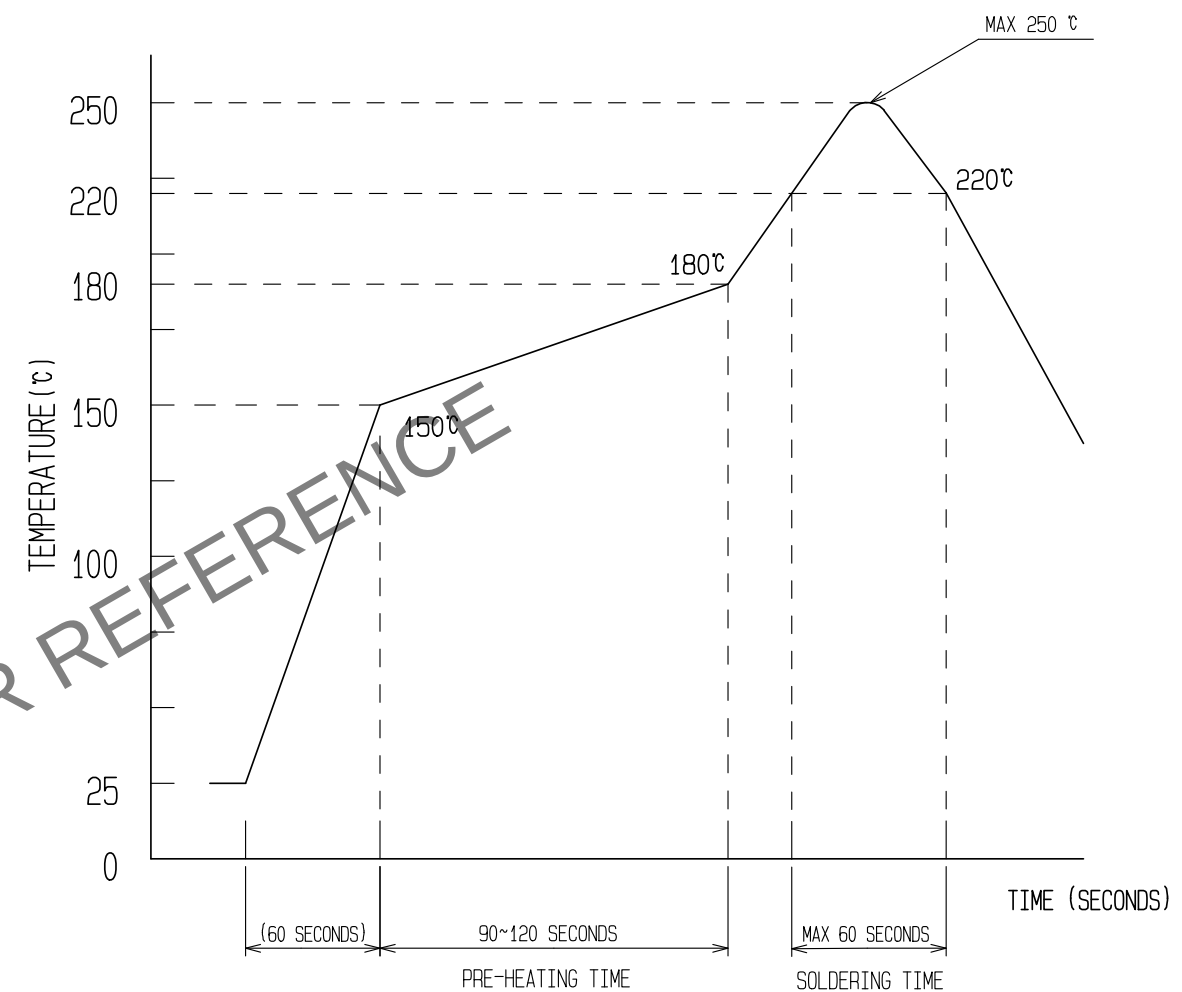


### ◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS :  $100 \mu\text{m}$



### 5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C, 60 SEC. MAX.  
(PEAK TEMPERATURE: 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150°C  
PRE-HEAT TEMPERATURE(MAX): 180°C  
PRE-HEAT TIME: 90-120 sec.

5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

**HRS**

|             |                          |
|-------------|--------------------------|
| DRAWING NO. | EDC-355885-53-01         |
| PART NO.    | BM15FR0.8-10DS-0.35V(53) |
| CODE NO.    | CL673-1225-5-53          |

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